

POWERING AI INFRASTRUCTURE WITH PRECISE THERMAL SENSING

Next-Gen Temperature Sensing for High Density AI Data Centers, Advanced Cooling, and Optical Systems

AI workloads...reliability and uptime

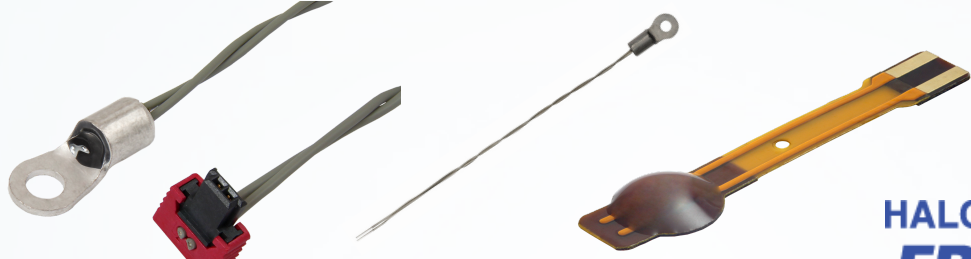


Adaptable designs



"From chip to rack to data center — thermal visibility that scales with AI."

NTCALUG / NTCAFLEX



HALOGEN
FREE
Available

Surface: direct sensing of modules and power conversion systems

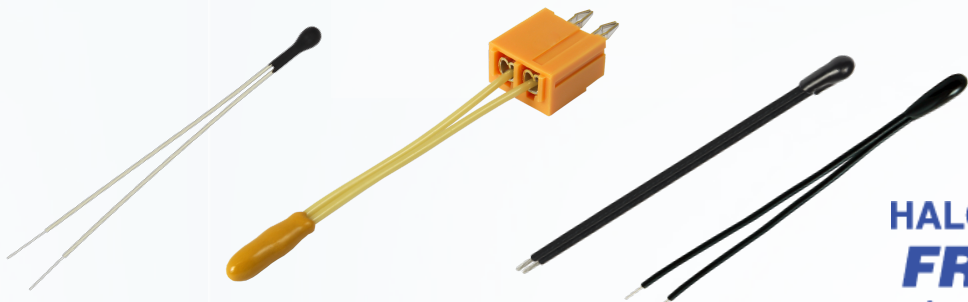


- Ease of integration on **busbar systems, heat sinks, and cold plates** for optimal thermal coupling
- Flexibility in design with custom options



[Product Page](#)

NTCLE



HALOGEN
FREE
Available

Ambient: rack-level and airflow monitoring to stabilize performance



- Fast reaction
- Limited thermal loss for accurate hot spot sensing
- Excellent performance in high humidity



[Product Page](#)

NTCAIMM



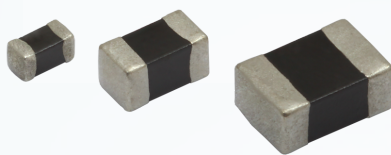
Immersion: in-flow measurement enabling next-gen cooling systems to drive AI efficiency

- Ease of integration for **liquid cooling inlets / outlets**
- Flexibility in design with custom options



[Product Page](#)

NTCS



On-PCB / On-FPC: pinpoint, fast-response sensing of power components

- **Sulfur-resistant** options
- Board flex resilient options
- Miniaturization with 0201 and 0402 case sizes for commercial-grade devices

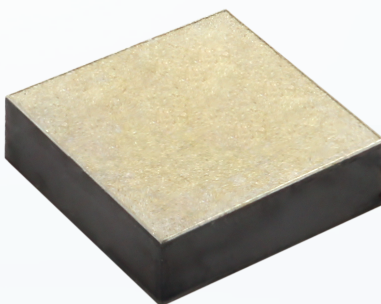


[Product Page](#)



[Product Page](#)

NTCC



Integrated On-Chip: ultra compact sensing embedded within semiconductor packages

- Close mounting proximity to **power components (embedded)**
- High temperature rating
- Excellent thermal coupling



[Product Page](#)

LINKS TO DESIGN TOOLS



[Design Tools](#)



[3D Models](#)

SPICE

[Models](#)

For questions: nlr@vishay.com